

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS

Claim 1-9. (cancelled)

Claim 10. (currently amended) A packaged semiconductor device comprising:
a semiconductor die;
a leadframe pad for supporting the semiconductor die;
a molded housing encapsulating the leadframe pad and semiconductor die;
a plurality of elongated leads each having an inner portion extending from a first end inside the molded housing, protruding through a side surface of the molded housing and terminating at a second end outside the housing to ~~from on~~ form an outer portion of each lead,

wherein a second lead is opposite to a third lead, wherein a first lead is disposed between the opposing second and third leads,

~~wherein a first lead is disposed with its inner portion in a central region of the molded housing and second and third leads are respectively disposed on opposite lateral sides of the central lead,~~

wherein the second and third leads each have a bent region along their respective lengths, said bent regions being adjacent to the side surface of the molded housing, the bent portions formed to increase a space between the first outer lead and the second and third leads,

wherein the outside molded housing is formed on the bent portion of the second and third leads and ~~wherein the molded housing is continuous between adjacent leads~~ inside the side surface of the packaged semiconductor device and is at least partially

discontinuous between at least two adjacent leads in a region of the leads outside the side surface of the packaged semiconductor device.

Claim 11. (cancelled)

Claim 12. (currently amended) The semiconductor package of claim 10 ~~11~~, wherein a distance between a surface of the molded housing covering the portion of the first outer lead and a surface of the molded housing covering ~~at least one of the bent~~ portions of the second and third outer leads is 1 mm or more.

Claim 13. (previously presented) The semiconductor package of claim 10, wherein a depression which is depressed toward a body of the molded housing is formed on at least one of a surface of the molded housing between the first outer lead and the second outer lead and a surface of the molded housing between the first outer lead and the third outer lead.

Claim 14. (currently amended) A semiconductor package in which a leadframe pad to which a semiconductor die is attached and inner leads electrically connected to the leadframe pad are covered by a molded housing, and outer leads extended from the inner leads protrude from a side surface of the molded housing to the outside, wherein a second lead is opposite to a third lead, wherein a first lead is disposed between the opposing second and third leads, wherein the outer leads include a first outer lead disposed in a central portion of the molded housing, second and third outer leads respectively disposed in a right and left of the first outer lead, wherein the second and third leads each have a bent region along their respective lengths, said bent regions being adjacent to the side surface of the molded housing, the bent portions formed to increase a space between the first outer lead and the bent portions of the second and third leads, wherein the outside molded housing is formed on the bent portion of the second and third leads and ~~wherein the molded housing~~ is continuous between adjacent leads inside the side surface of the packaged semiconductor device and is at least partially discontinuous

between at least two adjacent leads in a region of the leads outside the side surface of the packaged semiconductor device.

Claim 15. (previously presented) The semiconductor package of claim 14, wherein a portion where the first outer lead is adjacent to the side surface of the molded housing and is covered by the extended portion of the molded housing.

Claim 16. (currently amended) The semiconductor package of claim 15, wherein a distance between a surface of the molded housing covering the portion of the first outer lead and a surface of the molded housing covering ~~at least one of the~~ inclination portions of the second and third outer leads is 1 mm or more.

Claim 17. (previously presented) The semiconductor package of claim 14, wherein a depression which is depressed toward a body of the molded housing is formed on at least one of a surface of the molded housing between the first outer lead and the second outer lead and a surface of the molded housing between the first outer lead and the third outer lead.

Claim 18. (currently amended) The semiconductor package of claim 14, wherein the second and third outer leads have an inclination portion, wherein at least one of the inclination portions of the second and third outer leads includes a portion which is perpendicular to a surface of the molded housing and a flat portion which is larger than a thickness of the molded housing covering the inclination portions in a boundary between the inclination portions and the molded housing.

Claim 19. (currently amended) A semiconductor package in which a leadframe pad to which a semiconductor die is attached and inner leads electrically connected to the leadframe pad are covered by a molded housing, and outer leads extending from the inner leads protrude from a side surface of the molded housing to the outside,

wherein the outer leads include a first and second lead, wherein at least one of the first and second outer leads is covered by an extended portion of the molded housing where the extended portion is adjacent to the side surface of the molded housing[.]; and
wherein the second lead has a bent or inclination portion in a region adjacent to the side surface of the molded housing, the bent portion protruding to increase a space between the first outer lead and the bent portion in the molded housing; and
wherein the outside molded housing is formed on the bent portion of the second lead.

Claim 20. (cancelled)

Claim 21. (previously presented) The semiconductor package of claim 19 wherein the second lead has an inclination portion in which a distance between the first outer lead and the inclination portion becomes larger as a distance between the inclination portion and the side surface of the molded housing becomes smaller, and wherein the inclination portion is covered by the extended portion of the molded housing.

Claim 22. (previously presented) The semiconductor package of claim 19 wherein a depression which is depressed toward a body of the molded housing is formed on the surface of the molded housing between the first outer lead and the second outer lead.

Claim 23. (previously presented) The semiconductor package of claim 22 wherein the second lead has a bent portion in a portion where it is adjacent to the side surface of the molded housing, the bent portion protruding to increase a space between the first outer lead and the bent portion in the molded housing.

Claim 24. (previously presented) The semiconductor package of claim 22 wherein the second lead includes an inclination portion in which a distance between the first outer lead and the inclination portion becomes larger as a distance between the

inclination portion and the side surface of the molded housing becomes smaller, and wherein the inclination portion is covered by the extended portion of the molded housing.

Claim 25. (previously presented) The semiconductor package of claim 19 further including a third lead, wherein the third lead is disposed in a central portion of the molded housing and the first and second outer leads respectively are disposed to the right and left of the third lead.

Claim 26. (previously presented) The semiconductor package of claim 25 wherein at least one of the first and second leads has a bent portion in a region where the leads are adjacent to the side surface of the molded housing, the bent portion protruding to increase a space between the first outer lead and the bent portion in the molded housing,

Claim 27. (previously presented) The semiconductor package of claim 25 wherein at least one of first and second leads includes an inclination portion in which a distance between the third, central lead and the inclination portion becomes larger as a distance between the inclination portion and the side surface of the molded housing becomes smaller, and wherein the inclination portion is covered by the extended portion of the molded housing.

Claim 28. (previously presented) The semiconductor package of claim 27 wherein at least one of the inclination portions of the first and second outer leads includes a portion which is perpendicular to a surface of the molded housing and a flat portion which is larger than a thickness of the molded housing covering the inclination portions in a boundary between the inclination portions and the molded housing.

Claim 29. (previously presented) The semiconductor package of claim 25 wherein a depression which is depressed toward a body of the molded housing is formed on at least one of a surface of the molded housing between the first outer lead and the

second outer lead and a surface of the molded housing between the first outer lead and the third outer lead.

Claim 30. (previously presented) The semiconductor package of claim 29 wherein at least one of the first and second outer leads has a bent portion in a region where it is adjacent to the side surface of the molded housing, the bent portion protruding to increase a space between the third outer lead and the bent portion in the molded housing.

Claim 31. (previously presented) The semiconductor package of claim 29 wherein at least one of the first and second leads includes an inclination portion in which a distance between the third outer lead and the inclination portion becomes larger as a distance between the inclination portion and the side surface of the molded housing becomes smaller and wherein the inclination portion is covered by the extended portion of the molded housing.

Claim 32. (previously presented) The semiconductor package of claim 31 wherein at least one of the inclination portions of the first and second outer leads includes a region which is perpendicular to a surface of the molded housing and a flat portion which is larger than a thickness of the molded housing covering inclination portions in a boundary between the inclination portions and the molded housing.

Claim 33. (currently amended) A packaged semiconductor device comprising:

- a semiconductor die;
- a leadframe pad for supporting the semiconductor die;
- a molded housing encapsulating the leadframe pad and semiconductor die;
- a plurality of elongated leads each having an inner portion extending from a first end inside the molded housing, protruding through a side surface of the molded housing and terminating at a second end outside the housing to form an outer portion of each lead,

wherein a second lead is opposite to a third lead, wherein a first lead is disposed between the opposing second and third leads, wherein a first lead is disposed with its inner portion in a central region of the molded housing and second and third leads are respectively disposed on opposite lateral sides of the central lead,

wherein the second and third leads each have a bent region along their respective lengths, said bent regions being adjacent to the side surface of the molded housing, the bent portions formed to increase a space between the first outer lead and the second and third leads,

wherein at a region outside the side surface a portion of the molding housing extends longitudinally from the side surface to cover a portion of the leads adjacent and outside the side surface and said molding housing extends partially laterally toward an adjacent lead to leave at least a partial void of molding housing in a lateral direction between said partially covered lead and said adjacent lead.


Claim 34. (cancelled)

Claim 35. (currently amended) The semiconductor package of claim 33 ~~[[34]]~~ wherein a distance between a surface of the molded housing covering the portion of the first outer lead and a surface of the molded housing covering ~~at least one of the~~ bent portions of the second and third outer leads is 1 mm or more.

Claim 36. (previously presented) The semiconductor package of claim 33 wherein a depression which is depressed toward a body of the molded housing is formed on at least one of a surface of the molded housing between the first outer lead and the second outer lead and a surface of the molded housing between the first outer lead and the third outer lead.

Appl. No. 10/762,075
Resp. Dated May 25, 2006
Reply to Office Action of May 16, 2006

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